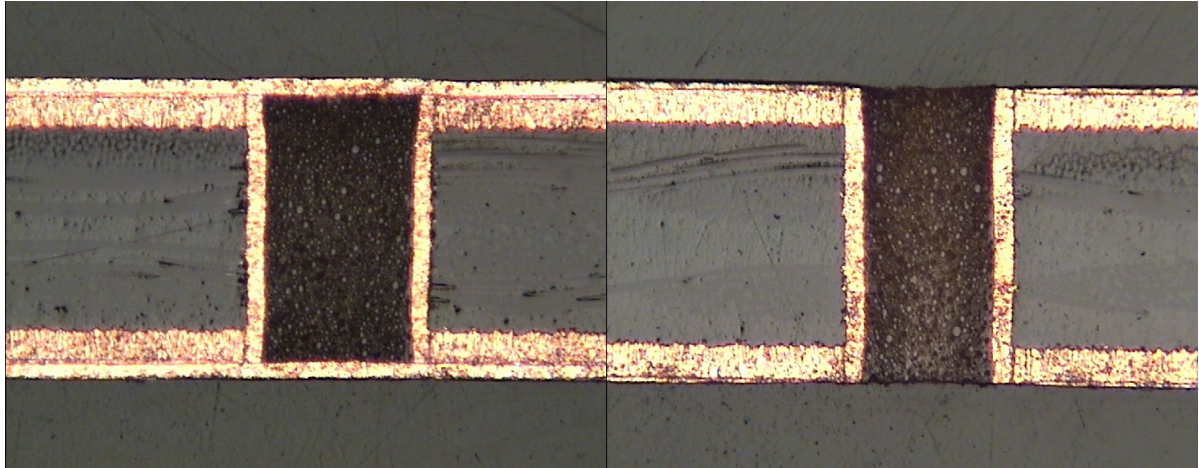


Via hole plugging



- for vacuum assembly
- better gluing
- better reliability of buried vias
- via in pad
- available conductive and non conductive
- minimum panel thickness: 0.2 mm

parameter for non conductive plugging:

- Tg 160°C
- CTE 32/115ppm
- Halogen Free and RoHS Compliant
- Pencil Hardness 7H

